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(54) **EMBEDDED PACKAGE STRUCTURE, POWER SUPPLY APPARATUS, AND ELECTRONIC DEVICE**

(57) This application provides an embedded package structure, a power supply apparatus, and an electronic device. First electronic components with smaller sizes are stacked, and then arranged in a substrate frame in a two-dimensional manner with a larger-size inductor component to form an embedded package structure. This can reduce an area occupied by the entire embedded package structure, and reduce an overall size of the structure, thereby facilitating integration and miniaturization. Then, a chip is disposed on the embedded package

structure, so that the chip serving as a main heat source is placed on a surface of the power supply apparatus. Compared with an existing power module structure in which a chip is embedded in a substrate to form an ECP module and an inductor is mounted on a surface of the ECP module, in the embedded package structure provided in this application, a main heat dissipation path of the chip is changed from an existing downward heat dissipation direction to an upward heat dissipation direction, which may improve a heat dissipation capability.

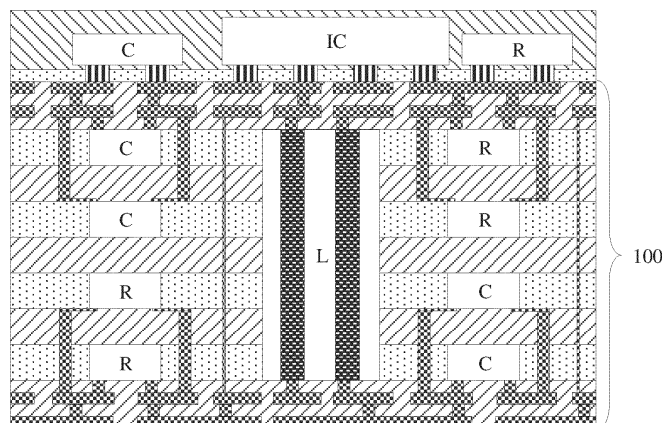


FIG. 8



## EUROPEAN SEARCH REPORT

Application Number

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Place of search <b>The Hague</b>		Date of completion of the search <b>12 March 2024</b>	Examiner <b>Kästner, Martin</b>
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document		T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons ..... & : member of the same patent family, corresponding document	

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